

<b>Form 1449 (Modified)</b> 12/22/2006 <b>Information Disclosure Statement By Applicant</b> (Use Several Sheets if Necessary)	Atty Docket No. <b>LAM1P177/P1139</b> Applicant: <b>KANG et al.</b> Filing Date <b>August 26, 2003</b>	Application No.: <b>10/648,953</b>  Group <b>2823</b>
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### U.S. Patent Documents

Examiner Initial	No.	Patent No.	Date	Patentee	Class	Sub-class	Filing Date
JM	A1.	2005/0164479A1	07/28/05	Perng et al.	438	591	01/27/04
	A2.						
	A3.						
	A4.						
	A5.						
	A6.						
	A7.						
	A8.						
	A9.						
	A10.						

### Foreign Patent or Published Foreign Patent Application

Examiner Initial	No.	Document No.	Publication Date	Country or Patent Office	Class	Sub-class	Translation	
							Yes	No
	B1.							
	B2.							
	B3.							
	B4.							
	B5.							

### Other Documents

Examiner Initial	No.	Author, Title, Date, Place (e.g. Journal) of Publication
JM	C1.	Eric Eisenbraun et al., "Atomic Layer Deposition (ALD) of Tantalum-based Materials for Zero Thickness Copper Barrier Applications", Proceedings of IEEE (2001), pages 207-209.
	C2.	
	C3.	
	C4.	

Examiner /Julio Maldonado/ (01/06/2007)	Date Considered 01/06/2007
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Examiner: Initial citation considered. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.